by reducing the modulus of elasticity of only the polishing surface in contact with an aqueous slurry, while maintaining high hardness for the polishing layer as a whole, it is possible to maintain high low-scratch property, while maintaining a high polishing rate and high planarization performance.

[0023]

Preferably, the polishing layer has a JIS-D hardness at 23°C when immersed in warm water at 50°C for 72 hours, of 45 to 75, in terms of particularly excellent high planarization performance and scratch resistance.

[0024]

Another aspect of the present invention is directed to a polishing pad including: a polishing layer including any one of the above-described polyurethanes for use in a polishing layer, and a cushioning layer having a hardness lower than a hardness of the polishing layer.

[Advantageous Effects of Invention]

[0025]

According to the present invention, it is possible to obtain a polishing layer having both a high polishing rate and excellent low-scratch property, and also exhibiting excellent planarization performance.

[Description of Embodiment]